

3D Power Electronics And Manufacturing Symposium Was A Great Success

by Arnold Alderman, Publicity Chair and Brian Narveson, Finance Chair, 3D PEIM

The PSMA-sponsored second International Symposium on 3D Power Electronics Integration and Manufacturing (3D PEIM) was another success! On June 25-27, 2018, over 70 participants, 22 from outside the U.S., attended the event in College Park, Maryland.

Prior to the technical program, three tutorials were given by leading experts on additive manufacturing and power electronics system integration: "Additive Manufacturing" by Christopher Williams of Virginia Tech; "System Integration" by Douglas Hopkins of NC State University; and "Integrated Thermal Packaging" by Michael Ohadi of the University of Maryland. Attendee reviews of the tutorials were outstanding with over 90% feeling that they increased their knowledge from the symposium.



3D PEIM attendees.

The symposium opened with two outstanding keynote talks given by two leading researchers in power packaging: "Small, Quiet, Robust, and Affordable: Delivering the Integrated Promise" by Mark Johnson, University of Nottingham, UK; and "Embedding Technologies for Planar Power Electronics Modules" by Rolf Aschenbrenner, Fraunhofer Institute-Berlin, Germany.

Attendees were able to attend every presentation in the 3D PEIM high-value single-track technical program featuring 34 oral presentations divided into eight topical sessions, each with a keynote speaker followed by three invited/contributed talks. Over 80% of the oral talks were invited.

The presenters and attendees engaged in lively discussions during the sessions and had many networking breaks. In addition, 19 posters were displayed during a meaningful interactive session with the displaying students. Participant feedback stated that 90% of attendees felt the presented material was high quality and they were interested in attending a future 3D-PEIM Symposium.

The presentations from this symposium are available to PSMA members and symposium attendees for six months after which they will be available to the public.



Discussion at Pink exhibit table.



A 3D-PEIM single track session.



A special thanks to Patrick McCluskey, General Chair (on right) and GQ Lu, Technical Program Chair (on left).

The symposium was sponsored by the Power Sources Manufacturers Association (www.pσμα.com), with IEEE EPS as a technical sponsor. It was also supported financially by two industry sponsors, Pink and Kemet, plus three academic sponsors—CALCE at the University of Maryland, CPES at Virginia Tech, and the FREEDM Systems Center at NCSU.

3D-PEIM 2020 will be held in Osaka, Japan. Planning for 2020 has begun. If you are interested in participating or sponsoring, please contact info@3D-PEIM.Org, or the PSMA office at power@psma.com.